

ZIITEK ELECTRONIC MATERIAL & TECHNOLOGY CO., LTD

TIF[™]700M Thermally Conductive Silicone Pads Series

time of the heat-generating electronic components.

TIFTM700M Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effecitly enhances the efficiency and life-

REV01



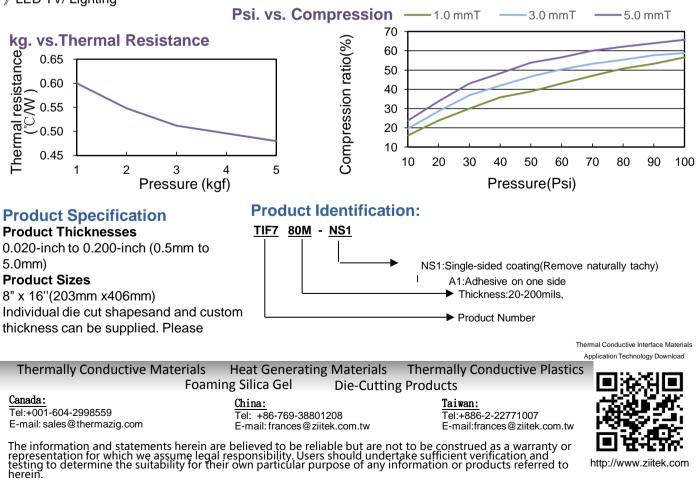
Features

- Good thermal conductivity: 6.0 W/mK
- » Naturally tacky needing no further adhesive coating
- Soft and Compressible for low stress >>> applications
- Available in varies thickness >>>

Application

- » Cooling components to the chassis of frame
- » Car Battery & Power Supply
- » Charging Pile
- Graphics Card Thermal Module >
- > Set Top Box
- » LED TV/ Lighting

Typical Properties of TIF[™]700M Series Color Gray Visual Ceramic filled silicone ****** Construction elastomer Thickness range 0.020"-0.200" ASTM D374 Hardness 55 Shore 00 ASTM 2240 Specific Gravity 3.25 g/cc ASTM D297 -40 ~200 °C ****** Operating Temp Dielectric Breakdown Voltage >5500 VAC ASTM D149 Dielectric Constant@1MHz 4.5 MHz ASTM D150 5. 2X10¹³ 0hm-cm ASTM D257 Volume Resistivity 6.0 W/mK ASTM D5470 Thermal Conductivity 6.0 W/mK GB/T 32064 Outgassing (TML) 0.30% ASTM E595 94 V0 GB/T 2408 Flame Rating



http://www.ziitek.com